



Material Content Data Sheet



Sales Product Name		XMC4504-F100F512 AC		Issued		19. January 2018		
MA#		MA001212298						
Package		PG-LQFP-100-11		Weight*		764.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	43.832	5.73	5.73	57314	57314
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		94	
	non noble metal	zinc	7440-66-6	0.286	0.04		374	
	non noble metal	iron	7439-89-6	5.726	0.75		7487	
wire	non noble metal	copper	7440-50-8	232.490	30.40	31.20	304003	311958
	non noble metal	copper	7440-50-8	1.941	0.25	0.25	2538	2538
	encapsulation	organic material	carbon black	1333-86-4	2.288	0.30		2992
encapsulation	plastics	epoxy resin	-	61.779	8.08		80782	
	inorganic material	silicondioxide	60676-86-0	393.554	51.45	59.83	514608	598382
leadfinish	non noble metal	tin	7440-31-5	9.873	1.29	1.29	12910	12910
plating	noble metal	silver	7440-22-4	2.029	0.27	0.27	2653	2653
glue	plastics	epoxy resin	-	2.723	0.36		3561	
	noble metal	silver	7440-22-4	8.170	1.07	1.43	10684	14245
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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